



- (51) International Patent Classification:
H01L 33/48 (2010.01)
- (21) International Application Number:
PCT/US2012/053706
- (22) International Filing Date:
4 September 2012 (04.09.2012)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:
61/623,488 12 April 2012 (12.04.2012) US
- (71) Applicant (for all designated States except US): **SAINT-GOBAIN PERFORMANCE PLASTICS CORPORATION** [US/US]; 1199 South Chillicothe Road, Aurora, Ohio 44202 (US).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): **BRAVET, David** [FR/US]; 17 O'Neil Drive, Westborough, Massachusetts 01581 (US). **ADAMKO, Michael, A.** [US/US]; 2D Levra Drive, Morristown, New Jersey 07960 (US).
- (74) Agents: **ABEL LAW GROUP, LLP** et al.; 8911 North Capital of Texas Hwy, Bldg. 4, Suite 4200, Austin, TX 78759 (US).
- (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

[Continued on next page]

(54) Title: METHOD OF MANUFACTURING LIGHT EMITTING DEVICE

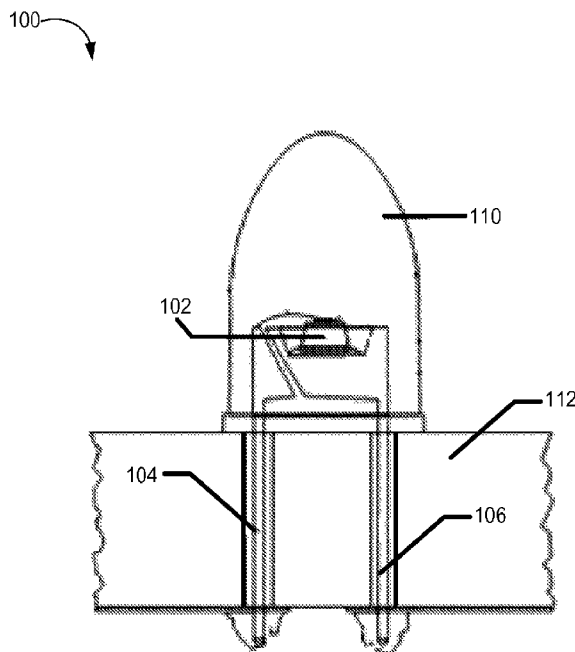


FIG. 1

(57) Abstract: A novel method of producing an encapsulated light emitting device. A preferred mold release film that can be used during the encapsulation of a LED chip has an elastic modulus and a glass transition temperature that are low enough as compared to the desired molding temperature that the release film will closely conform to the interior of the molding cavities used to form a protective lens surrounding an LED chip. A preferred release film according to embodiments of the present invention comprises a fully fluorinated polymer, such as a perfluoroalkoxy polymer, including MFA, or fluorinated ethylene propylene.

**Declarations under Rule 4.17:**

- *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*
- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

Published:

- *with international search report (Art. 21(3))*